

High Temperature (245 °C) Thick Film Chip Resistor

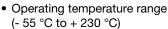


For applications such as down hole applications or aircraft breaking systems, the need for parts able to withstand very severe conditions (temperature as high as 230 °C powered or up to 245 °C un-powered) has leaded Vishay Sfernice to push out the limit of the thick film technology. Designers might read the application note "Power Dissipation Considerations in High Precision Vishay Sfernice Thin Film Chips Resistors and Arrays (P, PRA etc.) (High Temperature Applications)" (<u>www.vishay.com/doc?53047</u>) in conjunction with this data sheet to help them to properly design their PCBs and get the best performances of the CHPHT.

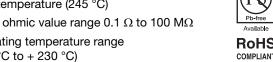
Vishay Sfernice R&D engineers will be willing to support any customer design considerations.

FEATURES

- High temperature (245 °C)
- Large ohmic value range 0.1 Ω to 100 M Ω

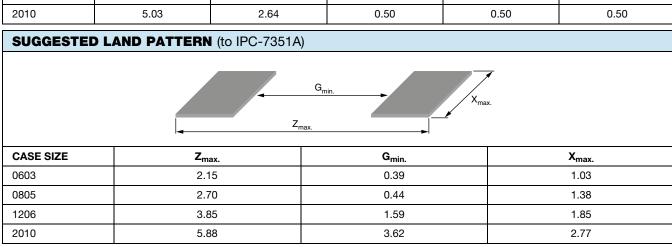


- SMD wraparound chip resistor
- Storage temperature range (- 55 °C to + 245 °C)
- Gold terminations for HMP process (< 1 µm thick) for temperature up to 245 °C
- Tin/silver terminations for operating temperature up to 200 °C
- Material categorization: For definitions of compliance please see www.vishav.com/doc?99912



Available
RoHS
HALOGEN
FREE

DIMENSIONS in millimeters							
		E A	В	c			
CACE CIZE	Α	В	С	D	E		
CASE SIZE	± 0.152	± 0.127	± 0.127	± 0.127	± 0.127		
0603	0603 1.60 0.90 0.38 0.31 0.40						
0805	1.85	1.25	0.38	0.31	0.50		
1206	3.00	1.73	0.38	0.40	0.50		
2010	5.03	2.64	0.50	0.50	0.50		







STANDAR	STANDARD ELECTRICAL SPECIFICATIONS								
MODEL	SIZE	RESISTANCE RANGE Ω	RATED POWER Pn W (at 230 °C)	LIMITING ELEMENT VOLTAGE V	MAX. OVERLOAD VOLTAGE V	TOLERANCE ± %	TEMPERATURE COEFFICIENT ± ppm/°C		
CHPHT	0603	0.1 to 25M	0.0125	50	100	1, 2, 5	100, 200		
CHPHT	0805	0.1 to 25M	0.02	150	300	1, 2, 5	100, 200		
CHPHT	1206	0.1 to 50M	0.025	200	400	1, 2, 5	100, 200		
CHPHT	2010	0.1 to 100M	0.1	200	400	1, 2, 5	100, 200		

CLIMATIC SPECIFICATIONS					
Operating temperature range - 55 °C to + 230 °C					
Storage temperature range	- 55 °C to + 245 °C				

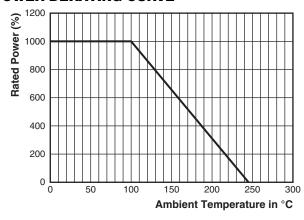
MECHANICAL SPECIFICATIONS				
Substrate	Alumina			
Technology	Thick film (Ruthenium oxyde)			
Protection	Parts have double and organic coating (0R5 to 100M)			
Terminations	N (W/A): SnAg over nickel barrier for temperature up to 200 °C G (W/A) type: Gold (< 1 µm) over nickel barrier for temperature up to 245 °C			

Note

 Refer to Application Note "Guidelines for Vishay Sfernice Resistive and Inductive Components" (document number: 52029) for recommended reflow profile. Profile #3 applies.

BEST TOL. AND TCR VERSUS OHMIC VALUE					
TIGHTEST TOLERANCE	OHMIC VALUES	BEST TCR ppm/°C			
1 % (F)	5 Ω < R < 10M	100 (K)			
2 % (G)	1 Ω < R < R max.	200 (L)			
5 % (J)	$0.1 \Omega < R < R \text{ max}.$	200 (L)			

POWER DERATING CURVE



PACKAGING

ESD packaging available: Waffle pack and plastic tape and reel (low conductivity). Paper tapes available on request (ESD only). (For 0603, 0805, and 1206 only.)

	NUMBER O			
SIZE	WAFFLE	TAPE A	ND REEL	TAPE WIDTH
	PACK	MIN.	MAX.	
0603			5000	
0805 0705	100	100	4000	8 mm
1206	140			
2010	60		2000	

PACKAGING RULES

Waffle Pack

Can be filled up to maximum quantity indicated in the table here above, taking into account the minimum order quantity. When quantity ordered exceeds maximum quantity of a single waffle pack, the waffle packs are stacked up on the top of each other and closed by one single cover.

To get "not stacked up" waffle pack in case of ordered quantity > maximum number of pieces per package: Please consult Vishay Sfernice for specific ordering code

Tape and Reel

Can be filled up to maximum quantity indicated in the table here above, taking into account the minimum order quantity. When quantity ordered is between the MOQ and the maximum reel capacity, only one reel is provided.

When several reels are needed for ordered quantity within MOQ and maximum reel capacity: Please consult Vishay Sfernice for specific ordering code





POPULAR OPTIONS

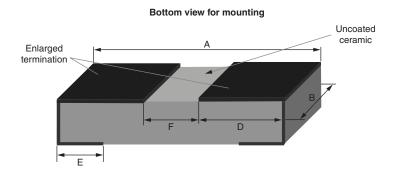
For any option it is recommended to consult Vishay Sfernice for availability first.

Option: Enlarged terminations:

For stringent and special power dissipation requirements, the thermal resistance between the resistive layer and the solder joint can be reduced using enlarged terminations chip resistors which are soldered on large and thick copper pads acting as heat sinks (see application note: "Power Dissipation in High Precision Vishay Sfernice Chip Resistors and Arrays (P Thin Film, PRA Arrays, CHP Thick Film" (www.vishay.com/doc?53048).

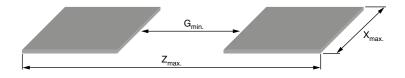
Option to order: 0063 (applies to size 1206/2010).

DIMENSIONS (Option 0063) in millimeters



	Α	В	E	D			
CASE SIZE	MAX. TOL. + 0.152 MIN. TOL. - 0.152	MAX. TOL. + 0.127 MIN. TOL. - 0.127	MAX. TOL. + 0.13 MIN. TOL. - 0.13	MAX. TOL. + 0.13 MIN. TOL. - 0.13	F		
	NOMINAL	NOMINAL	NOMINAL	NOMINAL	NOMINAL	MIN.	MAX.
1206	3.06 (0.120)	1.60 (0.063)	0.40 (0.016)	1.22 (0.048)	0.63 (0.024)	0.50 (0.020)	0.76 (0.030)
2010	5.08 (0.200)	2.54 (0.100)	0.48 (0.019)	2.23 (0.088)	0.63 (0.024)	0.50 (0.020)	0.76 (0.030)

SUGGESTED LAND PATTERN (Option 0063)

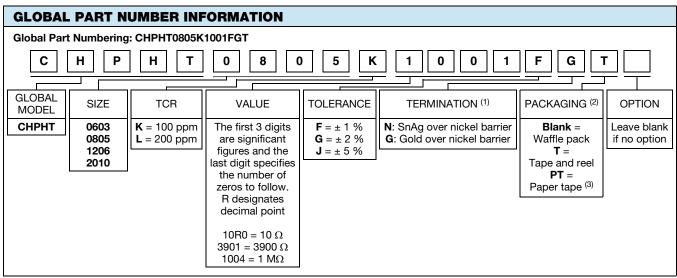


CHIP SIZE		DIMENSIONS (in millimeters)	
Chir Size	Z _{max.}	G _{min.}	X _{max.}
1206	3.91 (0.154)	0.50 (0.020)	1.73 (0.068)
2010	5.93 (0.233)	0.50 (0.020)	2.67 (0.105)



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PERFORMANCE					
TESTS	CONDITIONS	REQUIREMENTS	TYPICAL VALUES AND DRIFTS		
Termination adhesion	5N for 10 s	± (0.25 % + 0.05 Ω)	< ± 0.1 %		
Resistance to solder heat	Immersion 10 s in Sn/Pb 60/40 at + 260 °C	± (0.25 % + 0.05 Ω)	< ± 0.1 %		
Rapid temperature change	5 cycles - 55 °C to + 155 °C	± (0.25 % + 0.05 Ω)	< ± 0.1 %		
Climatic sequence	Phase A dry heat Phase B damp heat Phase C cold - 55 °C Phase D damp heat 5 cycles	± (1 % + 0.05 Ω)	< ± 0.2 %		
Humidity (steady state)	56 days	± (1 % + 0.05 Ω)	< ± 0.2 %		
Moisture resistance	AEC-Q200 85 °C/85 % RH/Pn 1000 h	3 % + 0.05 Ω	Max. < 3 % + 0.05 Ω		
Short time overload	6.25 Pn for 2 s	$\pm (0.25 \% + 0.05 \Omega)$	< ± 0.1 %		
Load life	1000 h at rated power at 230 °C	-	1 % max.		
Shelf life	1000 h at 245 °C	-	1 % max.		



Notes

- (1) N terminations for temperature up to 200 °C G terminations for temperature up to 230 °C
- (2) For specific quantity of parts per packaging please consult Vishay Sfernice
- (3) For paper tape please consult Vishay Sfernice



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